

International  
**IR** Rectifier

**SMPS MOSFET**

**IRF730A**

HEXFET® Power MOSFET

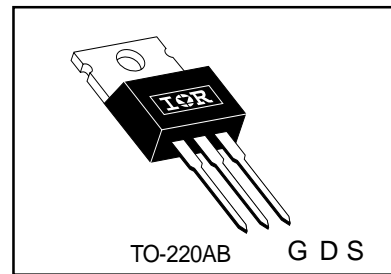
#### Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptable Power Supply
- High speed power switching

$V_{DSS}$	$R_{ds(on)}$ max	$I_D$
400V	1.0 $\Omega$	5.5A

#### Benefits

- Low Gate Charge  $Q_g$  results in Simple Drive Requirement
- Improved Gate, Avalanche and dynamic  $dv/dt$  Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective  $C_{oss}$  Specified (See AN1001)



#### Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D$ @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS}$ @ 10V	5.5	A
$I_D$ @ $T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS}$ @ 10V	3.5	
$I_{DM}$	Pulsed Drain Current ①	22	
$P_D$ @ $T_C = 25^\circ\text{C}$	Power Dissipation	74	W
	Linear Derating Factor	0.6	W/ $^\circ\text{C}$
$V_{GS}$	Gate-to-Source Voltage	$\pm 30$	V
$dv/dt$	Peak Diode Recovery $dv/dt$ ③	4.6	V/ns
$T_J$	Operating Junction and	-55 to + 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case )	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

#### Typical SMPS Topologies:

- Single Transistor Flyback Xfmr. Reset
- Single Transistor Forward Xfmr. Reset  
(Both US Line input only).

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**Static @ T<sub>J</sub> = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	400	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔV <sub>(BR)DSS/ΔT<sub>J</sub></sub>	Breakdown Voltage Temp. Coefficient	—	0.5	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DSON</sub>	Static Drain-to-Source On-Resistance	—	—	1.0	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.3A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0	—	4.5	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	25	μA	V <sub>DS</sub> = 400V, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 320V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	100	nA	V <sub>GS</sub> = 30V
	Gate-to-Source Reverse Leakage	—	—	-100		V <sub>GS</sub> = -30V

**Dynamic @ T<sub>J</sub> = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
g <sub>fs</sub>	Forward Transconductance	3.1	—	—	S	V <sub>DS</sub> = 50V, I <sub>D</sub> = 3.3A
Q <sub>g</sub>	Total Gate Charge	—	—	22	nC	I <sub>D</sub> = 3.5A
Q <sub>gs</sub>	Gate-to-Source Charge	—	—	5.8		V <sub>DS</sub> = 320V
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge	—	—	9.3		V <sub>GS</sub> = 10V, See Fig. 6 and 13 ④
t <sub>d(on)</sub>	Turn-On Delay Time	—	10	—	ns	V <sub>DD</sub> = 200V
t <sub>r</sub>	Rise Time	—	22	—		I <sub>D</sub> = 3.5A
t <sub>d(off)</sub>	Turn-Off Delay Time	—	20	—		R <sub>G</sub> = 12Ω
t <sub>f</sub>	Fall Time	—	16	—		R <sub>D</sub> = 57Ω, See Fig. 10 ④
C <sub>iss</sub>	Input Capacitance	—	600	—	pF	V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance	—	103	—		V <sub>DS</sub> = 25V
C <sub>riss</sub>	Reverse Transfer Capacitance	—	4.0	—		f = 1.0MHz, See Fig. 5
C <sub>oss</sub>	Output Capacitance	—	890	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 1.0V, f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	30	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 320V, f = 1.0MHz
C <sub>oss eff.</sub>	Effective Output Capacitance	—	45	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V to 320V ⑤
		—	—	—		

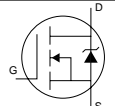
## Avalanche Characteristics

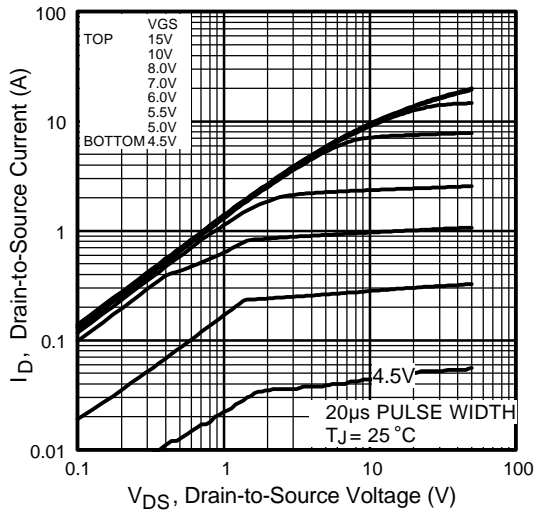
	Parameter	Typ.	Max.	Units
E <sub>AS</sub>	Single Pulse Avalanche Energy②	—	290	mJ
I <sub>AR</sub>	Avalanche Current①	—	5.5	A
E <sub>AR</sub>	Repetitive Avalanche Energy①	—	7.4	mJ

## Thermal Resistance

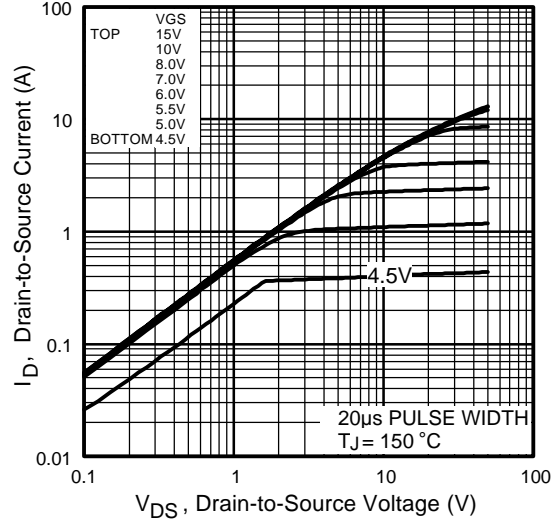
	Parameter	Typ.	Max.	Units
R <sub>θJC</sub>	Junction-to-Case	—	1.70	°C/W
R <sub>θCS</sub>	Case-to-Sink, Flat, Greased Surface	0.50	—	
R <sub>θJA</sub>	Junction-to-Ambient	—	62	

## Diode Characteristics

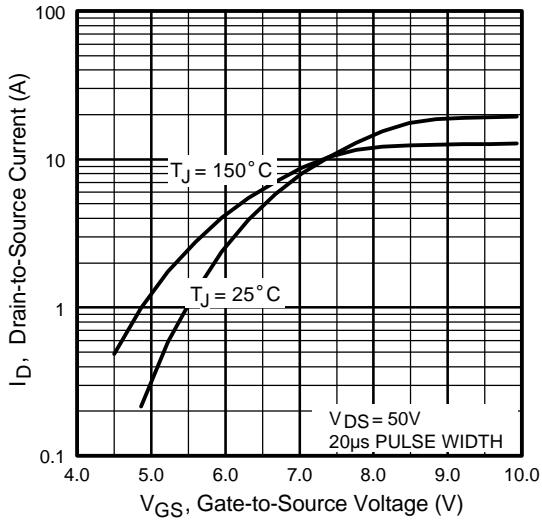
	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	5.5	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①	—	—	22		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.6	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 5.5A, V <sub>GS</sub> = 0V ④
t <sub>rr</sub>	Reverse Recovery Time	—	370	550	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 3.5A
Q <sub>rr</sub>	Reverse Recovery Charge	—	1.6	2.4	μC	di/dt = 100A/μs ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )				



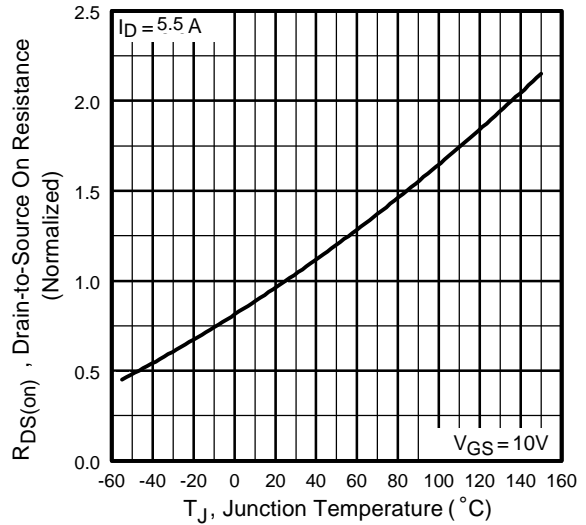
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics

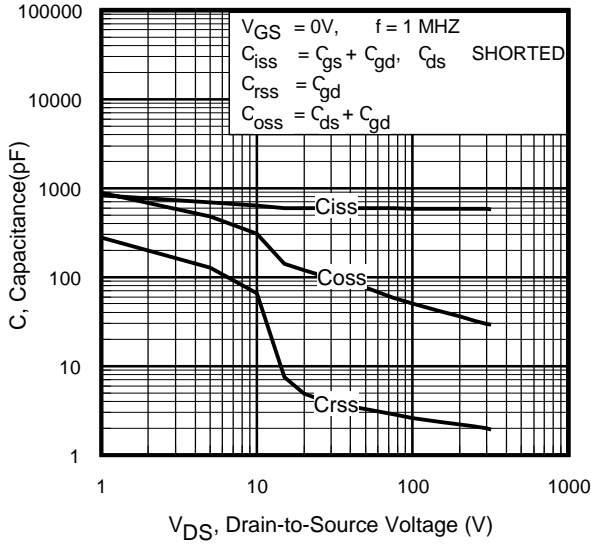


**Fig 3.** Typical Transfer Characteristics

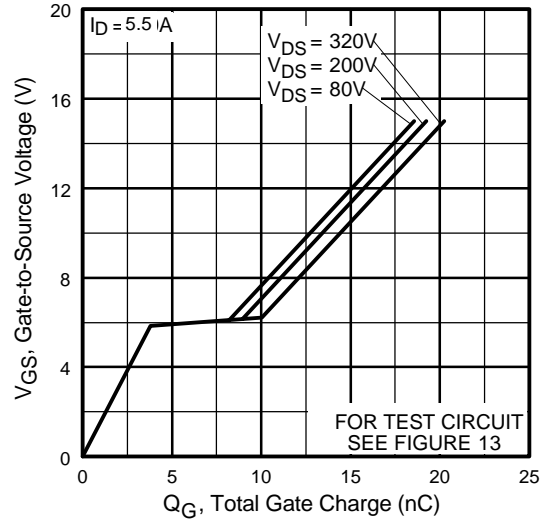


**Fig 4.** Normalized On-Resistance Vs. Temperature

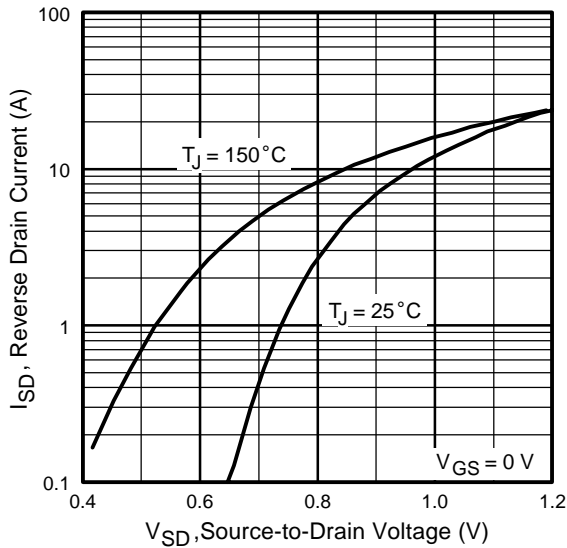
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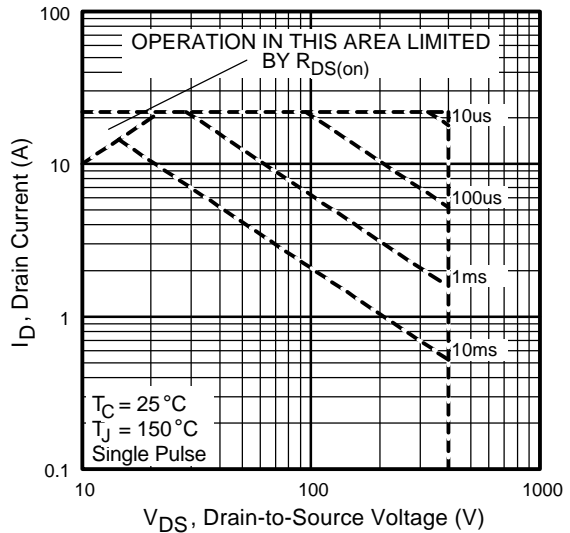
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



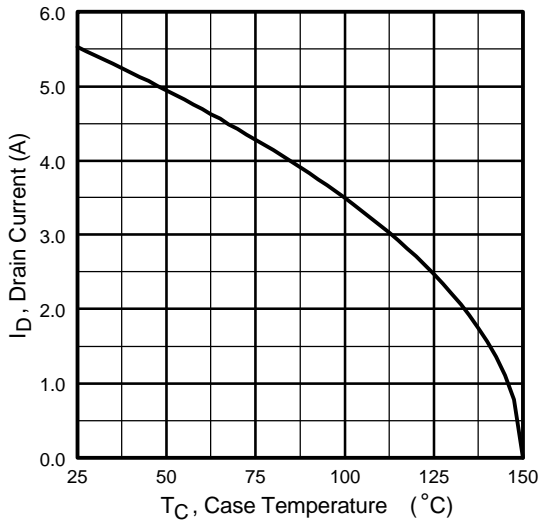
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



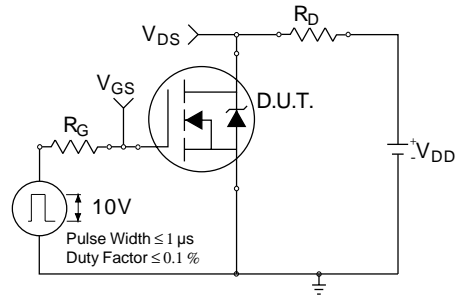
**Fig 7.** Typical Source-Drain Diode Forward Voltage



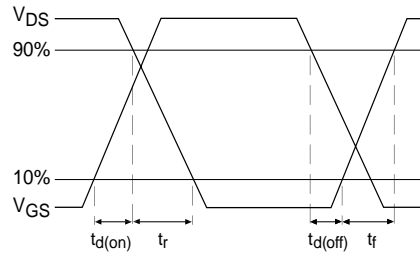
**Fig 8.** Maximum Safe Operating Area



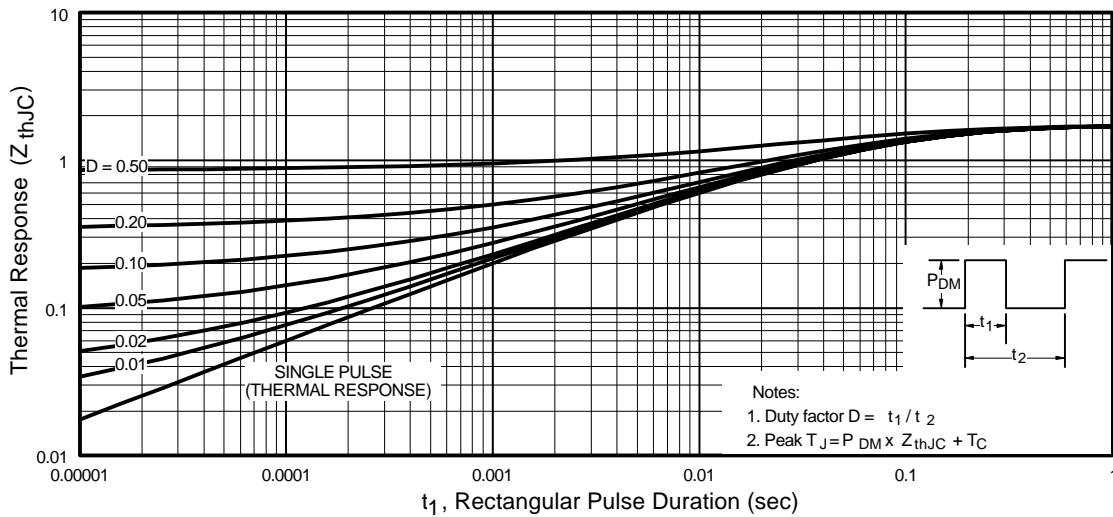
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit

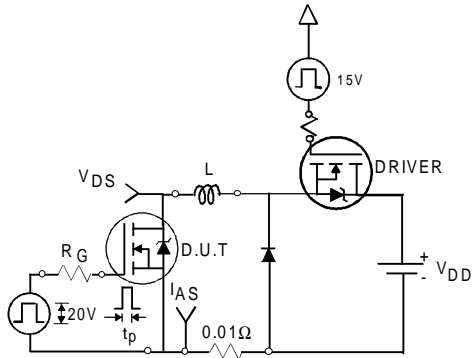


**Fig 10b.** Switching Time Waveforms

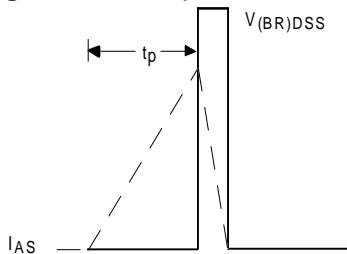


**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

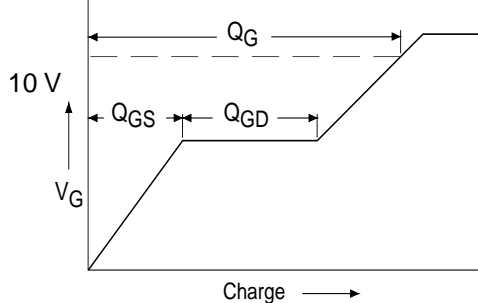
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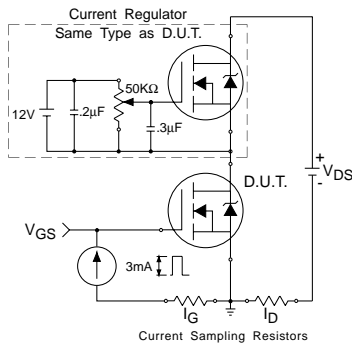
**Fig 12a.** Unclamped Inductive Test Circuit



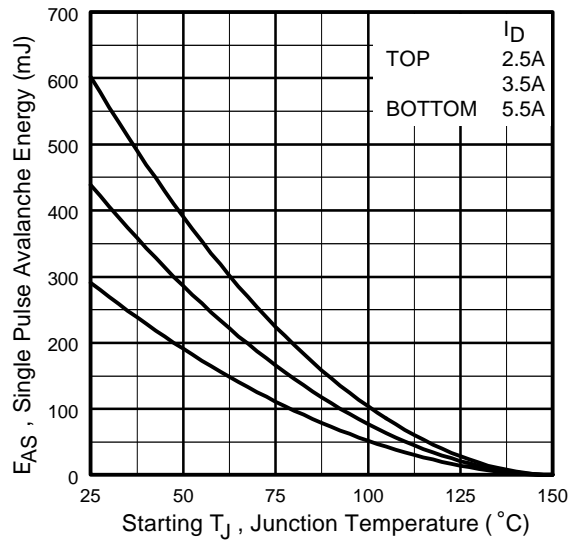
**Fig 12b.** Unclamped Inductive Waveforms



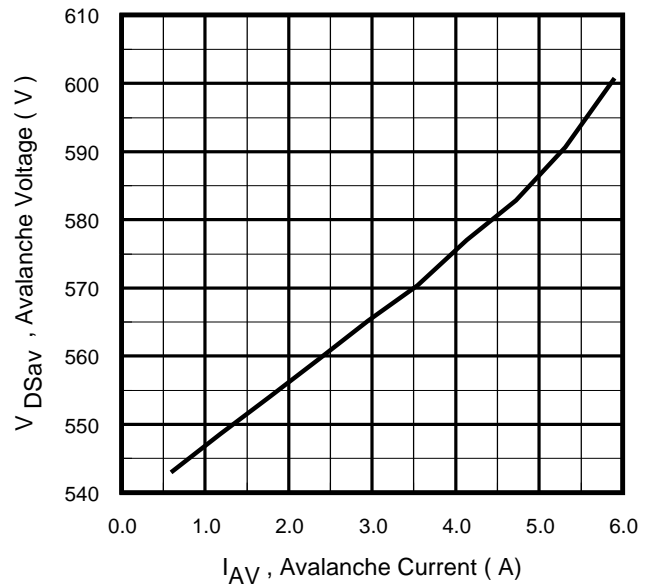
**Fig 13a.** Basic Gate Charge Waveform



**Fig 13b.** Gate Charge Test Circuit

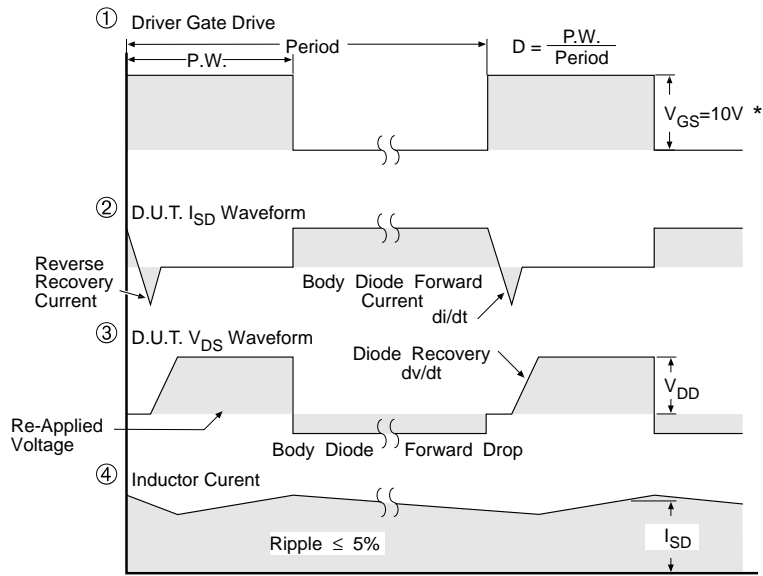
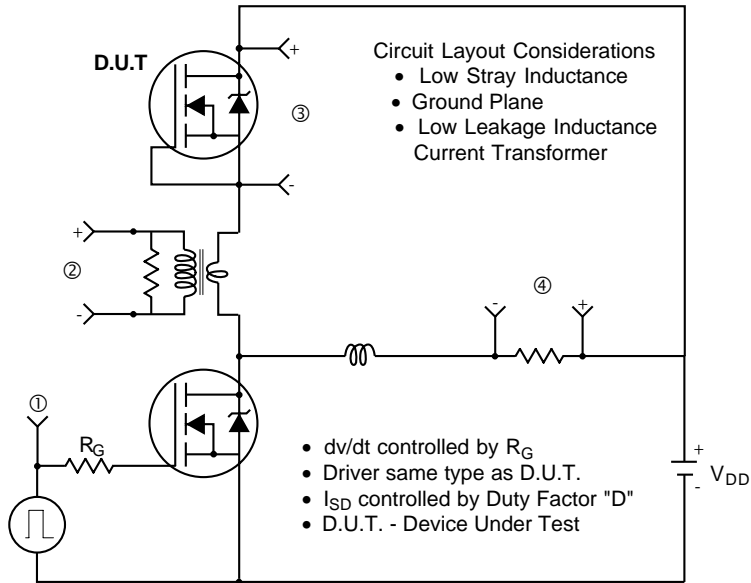


**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 12d.** Typical Drain-to-Source Voltage Vs. Avalanche Current

**Peak Diode Recovery dv/dt Test Circuit**



\*  $V_{GS} = 5V$  for Logic Level Devices

**Fig 14.** For N-Channel HEXFETS

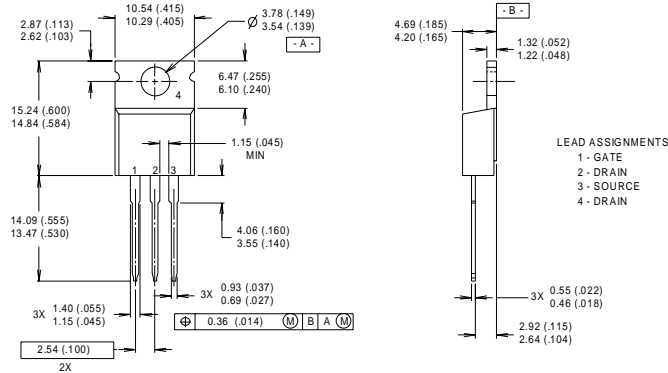
# IRF730A

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## Package Outline

### TO-220AB Outline

Dimensions are shown in millimeters (inches)

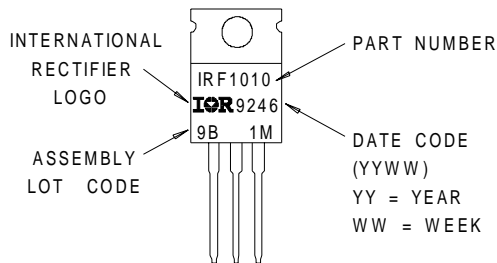


- NOTES:  
1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.  
2 CONTROLLING DIMENSION : INCH  
3 OUTLINE CONFORMS TO JEDEC OUTLINE TO-220AB.  
4 HEATSINK & LEAD MEASUREMENTS DO NOT INCLUDE BURRS.

## Part Marking Information

### TO-220AB

EXAMPLE : THIS IS AN IRF1010  
WITH ASSEMBLY  
LOT CODE 9B1M



#### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 19\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 5.5\text{A}$ . (See Figure 12)
- ③  $I_{SD} \leq 5.5\text{A}$ ,  $di/dt \leq 90\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  
 $T_J \leq 150^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ⑤  $C_{oss}$  eff. is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$

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**IR** Rectifier

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*Data and specifications subject to change without notice. 5/00*





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